

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
RYO SAEGUSA	07/14/2021
MASAYUKI MOCHIZUKI	07/14/2021
KEITA YAMAMOTO	07/13/2021
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<b>Name:</b>	FASFORD TECHNOLOGY CO., LTD.
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<b>City:</b>	MINAMI-ALPS CITY, YAMANASHI
<b>State/Country:</b>	JAPAN
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17399272
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<b>NAME OF SUBMITTER:</b>	MICHAEL H. JACOBS
<b>SIGNATURE:</b>	/Michael H. Jacobs/
<b>DATE SIGNED:</b>	08/11/2021
<b>Total Attachments: 1</b>	
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ASSIGNMENT  
( 譲渡証 )

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Fasford Technology Co., Ltd.  
a corporation organized under the laws of Japan,  
located at 610-5, Shimoimasuwa, Minami-Alps City, Yamanashi, Japan  
receipt of which is hereby acknowledged I do hereby sell and assign to said Fasford Technology Co., Ltd.  
its successor and assigns, all my right, title and interest, in and for the United States of America, in and to

**DIE BONDING APPARATUS AND MANUFACTURING METHOD FOR SEMICONDUCTOR  
DEVICE**

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,  
to be held and enjoyed by said Fasford Technology Co., Ltd.  
its successor, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Fasford Technology Co., Ltd.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Ryo SAEGUSA</u> Ryo SAEGUSA	<u>7/14/2021</u>
2) <u>Masayuki Mochizuki</u> Masayuki MOCHIZUKI	<u>7/14/2021</u>
3) <u>Keita Yamamoto</u> Keita YAMAMOTO	<u><del>Keita Yamamoto</del> 7/13/2021</u>
4) _____	_____
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____